Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2574	257/678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/31 10:41
L2	0	semiconductor with die with (metal adj layer) with (stamped adj bumps) with (die adj attach adj region) with height.clm.	US-PGPUB	OR	ON	2005/10/31 10:43
L3	2	"6893901"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/31 10:49
S1	10	("20020050912"|"20020074147"|"5892271"|"6133634"|"6144101").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 12:07
S2	0	"6893901"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/31 10:49
S3	0	"6893901"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 11:13
S4	0	"6893901"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 11:13
S5	2290	(chip or die) with carrier with bump	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 11:53
S6	4	(chip or die) with carrier with (stamped with bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 11:25
S7	33	S5 and stamped	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 11:32

S8	2	(chip or die) with carrier with (conical with bump)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 11:56
S9	10	"5123163"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 11:56
S10	2	"20020050912"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 12:08
S11	15	"5892271"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/10 12:08
S12	140	(vertical adj (mosfet or fet)) and (drain with bottom with contact)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/16 07:26
S13	0	S12 and (metal adj carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/16 07:26
S14	0	S12 and (metal with carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/16 07:26
S15	1	S12 and (heat adj sink)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/16 07:27